Product / Package Information

Package	LGA_CAV
Body Size (mm)	3.76 X 4.72 X 1.0
Ball Count	6
Terminal Finish	Gold

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Lid/Shield

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Stainless steel	Iron	7439-89-6	8.55 E-03	65.77	657692	25.47	254695
Stainless steel	Chromium	7440-47-3	2.37 E-03	18.20	182000	7.05	70481
Stainless steel	Nickel	7440-02-0	1.05 E-03	8.04	80400	3.11	31135
Stainless steel	Manganese	7439-96-5	1.41 E-04	1.09	10862	0.42	4206
Stainless steel	Silicon	7440-21-3	6.73 E-05	0.52	5177	0.20	2005
Stainless steel	Carbon	7440-44-0	5.00 E-06	0.04	385	0.01	149
Stainless steel	Nitrogen	7727-37-9	4.40 E-06	0.03	338	0.01	131
Stainless steel	Phosphorus	7723-14-0	3.20 E-06	0.025	246	0.010	95
Stainless steel	Molybdenum	7439-98-7	2.60 E-06	0.02	200	0.01	77
Stainless steel	Sulfur	7704-34-9	4.00 E-07	0.00	31	0.00	12
Nickel & its alloys	Nickel	7440-02-0	3.62 E-04	2.79	27854	1.08	10787
Tin & its alloys	Tin	7440-31-5	4.53 E-04	3.48	34815	1.35	13482
Subtotal			1.30 E-02	100.0	1000000	38.73	387256

Laminate

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Composite	Copper	7440-50-8	1.69 E-03	9.87	98700	5.04	50356
Composite	Bismaleimide Triazine resin, Epoxy resin	105391-33-1, 25722-66-1, 9003-36-5, NA	1.21 E-03	7.05	70500	3.60	35969
Composite	Continuous Filament Fiber Glass	65997-17-3	1.21 E-03	7.05	70500	3.60	35969
Composite	Inorganic Filler	21645-51-2, NA	7.24 E-04	4.23	42300	2.16	21581
	Laminate Subtotal		4.83 E-03	28.20	282000	14.39	143875
Other inorganic materials	Barium sulfate	7727-43-7	1.78 E-04	1.04	10400	0.53	5306
Other organic materials	Dipropylene glycol monomethyl ether	34590-94-8	9.59 E-05	0.56	5600	0.29	2857
Other organic materials	Epoxy resin (MW ≦700)	Proprietary	5.14 E-05	0.30	3000	0.15	1531
Other organic materials	Epoxy resin (MW ≦700, Carc. Cat. 3 ; R40, R43)	85954-11-6	3.60 E-05	0.21	2100	0.11	1071
Other inorganic materials	Talc containing no asbestiform fibers	14807-96-6	1.54 E-05	0.09	900	0.05	459
Other organic materials	Morpholine derivative	Proprietary	1.54 E-05	0.09	900	0.05	459
Other inorganic materials	Silica, amorphous		3.43 E-06	0.02	200	0.01	102
	Soldermask Subtotal	Proprietary	3.96 E-04	2.31	23100	1.18	11786
Copper & its alloys	Copper	7440-50-8	1.12 E-02	65.18	651800	33.25	332545
Nickel & its alloys	Nickel	7440-02-0	6.53 E-04	3.81	38100	1.94	19438
Precious Metals	Gold	7440-57-5	8.56 E-05	0.50	5000	0.26	2551
Subtotal			1.71 E-02	100.00	1000000	51.02	510195

Solder Land

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	5.90 E-04	73.68	736842	1.76	17575
Nickel & its alloys	Nickel	7440-02-0	1.70 E-04	21.05	210526	0.51	5064
Precious Metals	Gold	7440-57-5	3.00 E-05	5.26	52632	0.09	894
Subtotal			7.90 E-04	100.00	1000000	2.35	23533

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	9.90 E-05	99	990000	0.29	2949
Precious metals	Palladium	7440-05-3	1.00 E-06	1	10000	0.003	30
Subtotal			1.00 E-04	100	1000000	0.30	2979

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.30 E-03	100	1000000	3.87	38726

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	6.00 E-04	75.00	750000	1.79	17873
Other organic materials	Bisphenof F type epoxy resin	9003-36-5	8.00 E-05	10.00	100000	0.24	2383
Other organic materials	Bisphenof A type epoxy resin	25068-38-6	8.00 E-05	10.00	100000	0.24	2383
Others	Additives	Proprietary	2.40 E-05	3.00	30000	0.07	715
Others	Curing Agent	Proprietary	1.60 E-05	2.00	20000	0.05	477
Subtotal			8.00 E-04	100.00	1000000	2.38	23831

Die Coat

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Polydimethylsiloxane	68952-00-1	2.26 E-04	100	1000000	0.67	6717

Lid/ Shield Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.70 E-04	75.0	750000	0.51	5072
Other organic materials	Bisphenof F type epoxy resin	9003-36-5	2.27 E-05	10.0	100000	0.07	676
Other organic materials	Bisphenof A type epoxy resin	25068-38-6	2.27 E-05	10.0	100000	0.07	676
Others	Additives	Proprietary	6.81 E-06	3.0	30000	0.02	203
Others	Curing Agent	Proprietary	4.54 E-06	2.0	20000	0.01	135
Subtotal			2.27 E-04	100.00	1000000	0.68	6762

	Weight (g)	Percentage (%)	PPM
Package Totals	**3.36 E-02**	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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